

What Is Claimed Is:

1. A method for manufacturing a head suspension for supporting a head slider over a disk in a dynamic storage device, the method comprising the steps of:

providing a head suspension component;

forming a compliant locating feature within the head suspension component, the compliant locating feature including a plurality of spring beam tabs defined by an aperture and positioned to extend toward an opening;

receiving a tapered cylindrical pin through the opening of the compliant locating feature; and

locating the head suspension component precisely relative to a desired reference by positioning the head suspension component on the tapered pin at a predetermined location with the spring beam tabs engaging the tapered pin.

2. The method of claim 1, wherein the desired reference comprises the tapered pin.

3. The method of claim 1, wherein the head suspension component is a first head suspension component and the method further comprises the step of providing a second head suspension component, with the compliant locating feature being formed within one of the first and second head suspension components.

4. The method of claim 3, wherein the desired reference comprises the other of the first and second head suspension components.

5. The method of claim 3, wherein the compliant locating feature comprises a first compliant locating feature and wherein the method further comprises the step of forming a second compliant locating feature in one of the first and second head suspension components.

6. The method of claim 5, wherein the first and second compliant locating features are formed within the first and second head suspension components, respectively.

7. The method of claim 6, further comprising the step of forming at least one additional compliant locating feature in one of the first and second head suspension components, the at least one additional compliant locating feature including a plurality of spring beam tabs defined by an aperture and positioned to extend toward an opening.

8. The method of claim 6, wherein the step of receiving further comprises receiving the tapered pin through the openings of both the first and second compliant locating features and wherein the step of locating further comprises positioning the first and second head suspension components on the tapered pin at a predetermined location with the plurality of spring beam tabs of both the first and second compliant locating features engaging the tapered pin.

9. The method of claim 1, further comprising the step of performing subsequent manufacturing processes after locating the head suspension component relative to the desired reference.

10. The method of claim 1, wherein the component is removed from a carrier portion.

11. The method of claim 1, further comprising the step of removing the component from a carrier portion.